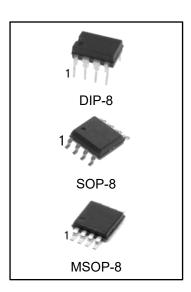


# **CMOS** general purpose timer

#### **Features**

- Exact equivalent in most cases for SE/NE555.
- Low Supply Current.
- High speed operation 500 kHz guaranteed.
- Wide operation supply voltage range 2 to 18 volts.
- Timing from microseconds through hours.
- Operates in both astable and monostable modes.
- Adjustable duty cycle.
- High output source/sink driver can drive TTL/CMOS



## **Ordering Information**

DEVICE	Package Type	MARKING	Packing	Packing Qty
TLC555PG	DIP-8	TLC555	TUBE	2000pcs/box
TLC555DRG	SOP-8	TLC555	REEL	2500pcs/reel
TLC555DGKRG	MSOP-8	C555	REEL	3000pcs/reel

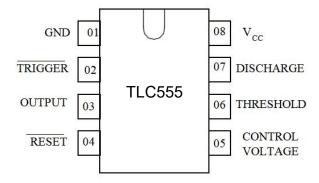


### **General Description**

The TLC555 is CMOS RC timers providing significantly improved performance over the standard SE/NE555 and 355 timers, while at the same time being direct replacements for those devices in most applications. Improved parameters include low supply current, wide operating supply voltage range, low THRESHOLD, TRIGGER and RESET currents, no crowbarring of the supply current during output transitions, higher frequency performance and no requirement to decouple CONTROL VOLTAGE for stable operation.

Specifically, the TLC555 is stable controller capable of producing accurate time delays of frequencies.

### **Pin Assignment**



#### **Truth Table**

THRESHOLD	TRIGGER	RESET	OUTPUT	DISCHARGE
X	X	L	L	ON
> 2/3 V <sub>CC</sub>	> 1/3 V <sub>CC</sub>	Н	L	ON
< 2/3 V <sub>CC</sub>	> 1/3 V <sub>CC</sub>	Н	STABLE	STABLE
X	< 1/3 V <sub>CC</sub>	Н	Н	OFF



# **Maximum Ratings And Recommended Operating Conditions**

		Recomn operating c		Maximum ratings		
Parameter, unit	Symbol	Val	ue	Val	ue	
		min	max	min	max	
Supply Voltage, V	VCC	2.0	18.0	0	18.0	
Output Current, mA	Io	-	20	-	100	
Input Voltage, V	VTH, VTRIG, VRST	-	-	-0.3	V <sub>CC</sub> +0.3	
Power Dissipation, mW	P <sub>D</sub>	-	-	-	200	
Operating Temperature,°C	TOPR	-40	85	-40	85	
Storage Temperature,°C	TSTG	-	-	-65	150	
Lead Temperature, 1 mm from Case for 10 Seconds,°C	TSOLDER	-	-		245	

**Note**: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured.



Dc Electrical Characteristics (Voltages Referenced to GND)

Parameter units	Symbol	Test Condit	ions	Val	Value		
Parameter, units	Symbol	IOL, IOH	VCC, B	min	max	rature, °C	
Threshold Voltage, V	VTH		5.0	0.65 V <sub>CC</sub>	0.70 V <sub>CC</sub>	$25\pm10$	
Threshold voltage, v	V 111		3.0	0.60 V <sub>CC</sub>	0.80 V <sub>CC</sub>	-20, 70	
Trigger voltage, V	VTRIG		5.0	0.31 V <sub>CC</sub>	0.36 V <sub>CC</sub>	25±10	
Trigger voitage, v	VING		3.0	0.28 V <sub>CC</sub>	0.40 V <sub>CC</sub>	-20, 70	
			2.0	0.4	1.0	25±10	
Reset voltage, V	VRST		18.0	0.4	1.0	23 ± 10	
reset voltage, v	*1(01		2.0	0.2	1.5	-20, 70	
			18.0	0.2	1.5	-20, 70	
Control Voltage Lead, V	VCV			0.65 V <sub>CC</sub>	0.69 V <sub>CC</sub>	25 10	
Control voltage Lead, v	•6•			0.60 V <sub>CC</sub>	0.80 V <sub>CC</sub>	-20, 70	
	VoL	$I_{OL}$ = 3.2 mA	5.0		0.4	25±10	
Output voltage Low, V		I <sub>OL</sub> = 20 mA	15.0		1.0	20 10	
Output voltage Low, v		I <sub>OL</sub> = 3.2 mA	5.0		0.6	-20, 70	
		I <sub>OL</sub> = 20 mA	15.0		1.5	-20, 70	
			5.0	4.0		25±10	
Output voltage High, V	Voн	I <sub>OH</sub> = -0.8 mA	15.0	14.3		23 ± 10	
Output voltage riigh, v	٧٥١١	Юн – -0.0 ПТА	5.0	3.5		-20, 70	
			15.0	14.0		-20, 70	
			2.0		200	25±10	
Supply Current, µA	ICC		18.0		300	23 10	
	ICC		2.0		400	-20, 70	
			18.0		600	-20, 10	



### **Ac Electrical Characteristics**

		Test Conditions	Va	Tempe-		
Parameter, unit	Symbol	R <sub>L</sub> , C <sub>L</sub>	VCC, V	Min	Max	rature, °C
Rise (Fall) Time of	tTHL,	$R_L = 10 \text{ M}\Omega$ , $C_L = 10 \text{ pF}$	5.0	35	75	25±10
Output,ns	tTLH	- , - ,		70	150	-20, 70
Guaranteed Max	fMAX	Astable Operation	2.0-	500		25±10
Osc Freq,kHz		- 1	18.0	200		-20, 70
Initial accuracy, %				5		
Drift with Tomporature			5.0		0.02	
Drift with Temperature,	αf	R∟ = 1 - 100 kΩ	10.0		0.03	-20, 70
707 0		C∟= 0.1 µF	15.0		0.06	
Drift with Supply Voltage,	$\Delta f$		5.0		3	25±10
%/B	ΔΙ		5.0		6	-20, 70

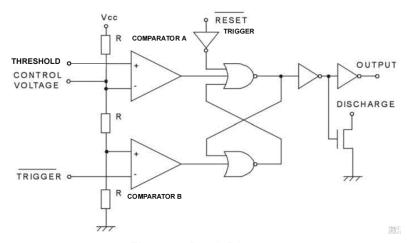


Figura 1. Block Diagram

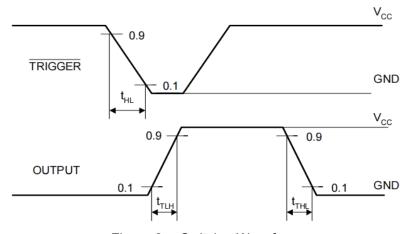
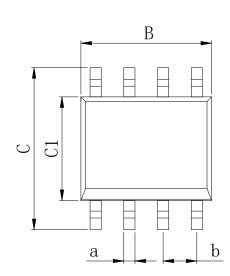


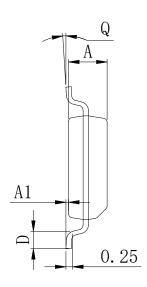
Figura 2. Switcing Waveforms



# **Physical Dimensions**

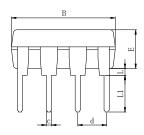
### SOP-8



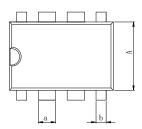


Dimensions In Millimeters(SOP-8)										
Symbol:	Α	A1	В	С	C1	D	Q	а	b	
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC	
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	1.27 650	

### DIP-8





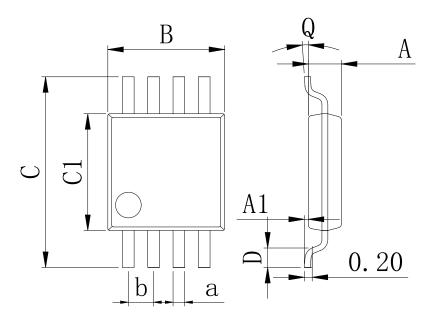


Dimensions In Millimeters(DIP-8)											
Symbol:	Α	В	D	D1	Е	L	L1	а	b	С	р
Min:	6.10	9.00	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2 E4 BCC
Max:	6.68	9.50	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	2.54 BSC



# **Physical Dimensions**

MSOP-8



Dimensions In Millimeters(MSOP-8)										
Symbol:	Α	A1	В	С	C1	D	Q	а	b	
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65 BSC	
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	0.00 BSC	



# **Revision History**

DATE	REVISION	PAGE		
2015-3-6	New	1-9		
2022 0 44	Update encapsulation type、Update Lead Temperature、Updated DIP-8 dimension、	1, 3, 6		
2023-9-14	Add annotation for Maximum Ratings.			



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